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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1713-i-ss

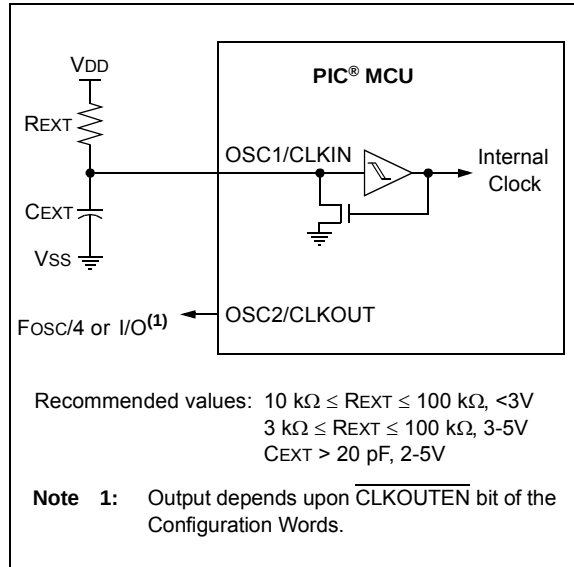
6.2.1.6 External RC Mode

The external Resistor-Capacitor (EXTRC) mode supports the use of an external RC circuit. This allows the designer maximum flexibility in frequency choice while keeping costs to a minimum when clock accuracy is not required.

The RC circuit connects to OSC1. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. The function of the OSC2/CLKOUT pin is determined by the CLKOUTEN bit in Configuration Words.

Figure 6-6 shows the external RC mode connections.

FIGURE 6-6: EXTERNAL RC MODES



The RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) and capacitor (C_{EXT}) values and the operating temperature. Other factors affecting the oscillator frequency are:

- threshold voltage variation
- component tolerances
- packaging variations in capacitance

The user also needs to take into account variation due to tolerance of external RC components used.

6.2.2 INTERNAL CLOCK SOURCES

The device may be configured to use the internal oscillator block as the system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in Configuration Words to select the INTOSC clock source, which will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to the internal oscillator during run-time. See **Section 6.3 “Clock Switching”** for more information.

In INTOSC mode, OSC1/CLKIN is available for general purpose I/O. OSC2/CLKOUT is available for general purpose I/O or CLKOUT.

The function of the OSC2/CLKOUT pin is determined by the CLKOUTEN bit in Configuration Words.

The internal oscillator block has two independent oscillators and a dedicated Phase-Lock Loop, HFPLL that can produce one of three internal system clock sources.

1. The **HFINTOSC** (High-Frequency Internal Oscillator) is factory calibrated and operates at 16 MHz. The HFINTOSC source is generated from the 500 kHz MFINTOSC source and the dedicated Phase-Lock Loop, HFPLL. The frequency of the HFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 6-3).
2. The **MFINTOSC** (Medium Frequency Internal Oscillator) is factory calibrated and operates at 500 kHz. The frequency of the MFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 6-3).
3. The **LFINTOSC** (Low-Frequency Internal Oscillator) is uncalibrated and operates at 31 kHz.

REGISTER 11-20: ANSEL: PORTC ANALOG SELECT REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	U-0	U-0
ANSC7	ANSC6	ANSC5	ANSC4	ANSC3	ANSC2	—	—
bit 7						bit 0	

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-2 **ANSC<7:0>**: Analog Select between Analog or Digital Function on pins RC<7:0>, respectively⁽¹⁾
 0 = Digital I/O. Pin is assigned to port or digital special function.
 1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.

bit 1-0 **Unimplemented**: Read as '0'

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

REGISTER 11-21: WPUC: WEAK PULL-UP PORTC REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
WPUC7	WPUC6	WPUC5	WPUC4	WPUC3	WPUC2	WPUC1	WPUC0
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **WPUC<7:0>**: Weak Pull-up Register bits
 1 = Pull-up enabled
 0 = Pull-up disabled

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
Note 2: The weak pull-up device is automatically disabled if the pin is configured as an output.

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REGISTER 11-22: ODCONC: PORTC OPEN-DRAIN CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ODC7	ODC6	ODC5	ODC4	ODC3	ODC2	ODC1	ODC0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

u = Bit is unchanged

x = Bit is unknown

-n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set

'0' = Bit is cleared

bit 7-0

ODC<7:0>: PORTC Open-Drain Enable bits

For RC<7:0> pins, respectively

1 = Port pin operates as open-drain drive (sink current only)

0 = Port pin operates as standard push-pull drive (source and sink current)

REGISTER 11-23: SLRCONC: PORTC SLEW RATE CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
SLRC7	SLRC6	SLRC5	SLRC4	SLRC3	SLRC2	SLRC1	SLRC0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

u = Bit is unchanged

x = Bit is unknown

-n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set

'0' = Bit is cleared

bit 7-0

SLRC<7:0>: PORTC Slew Rate Enable bits

For RC<7:0> pins, respectively

1 = Port pin slew rate is limited

0 = Port pin slews at maximum rate

REGISTER 11-24: INLVLC: PORTC INPUT LEVEL CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
INLVLC7	INLVLC6	INLVLC5	INLVLC4	INLVLC3	INLVLC2	INLVLC1	INLVLC0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

u = Bit is unchanged

x = Bit is unknown

-n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set

'0' = Bit is cleared

bit 7-0

INLVLC<7:0>: PORTC Input Level Select bits

For RC<7:0> pins, respectively

1 = ST input used for PORT reads and interrupt-on-change

0 = TTL input used for PORT reads and interrupt-on-change

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TABLE 13-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPT-ON-CHANGE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	120
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	126
ANSELC	ANSC7	ANSC6	ANSC5	ANSC4	ANSC3	ANSC2	—	—	131
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	83
IOCAF	IOCAF7	IOCAF6	IOCAF5	IOCAF4	IOCAF3	IOCAF2	IOCAF1	IOCAF0	143
IOCAN	IOCAN7	IOCAN6	IOCAN5	IOCAN4	IOCAN3	IOCAN2	IOCAN1	IOCAN0	142
IOCAP	IOCAP7	IOCAP6	IOCAP5	IOCAP4	IOCAP3	IOCAP2	IOCAP1	IOCAP0	142
IOCBF	IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0	144
IOCBN	IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0	144
IOCBP	IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0	143
IOCCF	IOCCF7	IOCCF6	IOCCF5	IOCCF4	IOCCF3	IOCCF2	IOCCF1	IOCCF0	146
IOCCN	IOCCN7	IOCCN6	IOCCN5	IOCCN4	IOCCN3	IOCCN2	IOCCN1	IOCCN0	145
IOCCP	IOCCP7	IOCCP6	IOCCP5	IOCCP4	IOCCP3	IOCCP2	IOCCP1	IOCCP0	145
IOCEF	—	—	—	—	IOCEF3	—	—	—	147
IOCEN	—	—	—	—	IOCEN3	—	—	—	147
IOCEP	—	—	—	—	IOCEP3	—	—	—	146
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	119
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	125
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	130

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupt-on-change.

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15.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "Use and Calibration of the Internal Temperature Indicator" (DS01333) for more details regarding the calibration process.

15.1 Circuit Operation

Figure 15-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 15-1 describes the output characteristics of the temperature indicator.

EQUATION 15-1: VOUT RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$
Low Range: $V_{OUT} = V_{DD} - 2V_T$

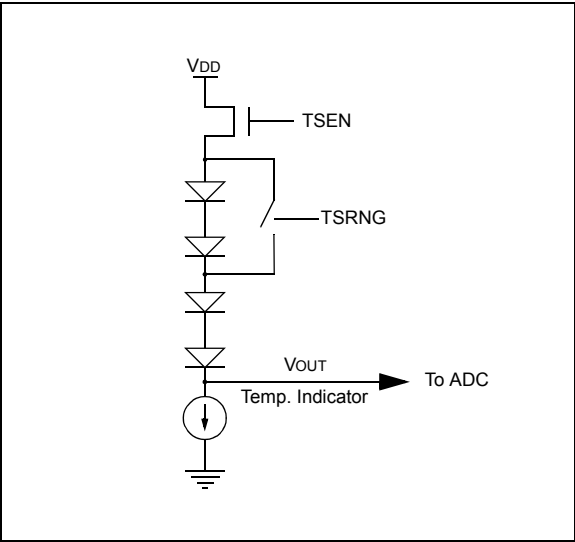
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher VDD is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 15-1: TEMPERATURE CIRCUIT DIAGRAM



15.2 Minimum Operating VDD

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 15-1 shows the recommended minimum VDD vs. range setting.

TABLE 15-1: RECOMMENDED VDD VS. RANGE

Min. VDD, TSRNG = 1	Min. VDD, TSRNG = 0
3.6V	1.8V

15.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 21.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

16.8 Comparator Response Time

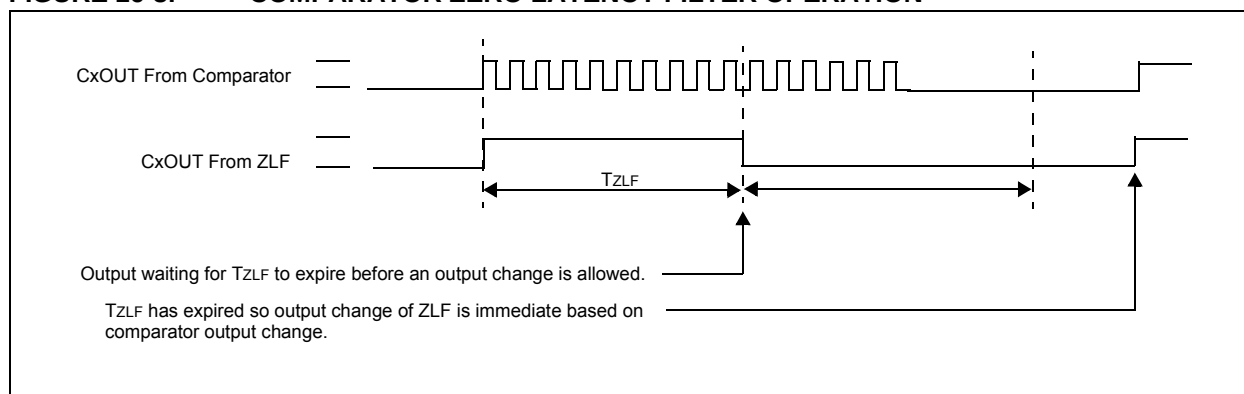
The comparator output is indeterminate for a period of time after the change of an input source or the selection of a new reference voltage. This period is referred to as the response time. The response time of the comparator differs from the settling time of the voltage reference. Therefore, both of these times must be considered when determining the total response time to a comparator input change. See the Comparator and Voltage Reference Specifications in Table 34-18: Comparator Specifications for more details.

the hardware and software relying on this signal. Therefore, a digital filter has been added to the comparator output to suppress the comparator output oscillation. Once the comparator output changes, the output is prevented from reversing the change for a nominal time of 20 ns. This allows the comparator output to stabilize without affecting other dependent devices. Refer to Figure 16-3.

16.9 Zero Latency Filter

In high-speed operation, and under proper circuit conditions, it is possible for the comparator output to oscillate. This oscillation can have adverse effects on

FIGURE 16-3: COMPARATOR ZERO LATENCY FILTER OPERATION



19.0 CONFIGURABLE LOGIC CELL (CLC)

The Configurable Logic Cell (CLCx) provides programmable logic that operates outside the speed limitations of software execution. The logic cell takes up to 32 input signals and, through the use of configurable gates, reduces the 32 inputs to four logic lines that drive one of eight selectable single-output logic functions.

Input sources are a combination of the following:

- I/O pins
- Internal clocks
- Peripherals
- Register bits

The output can be directed internally to peripherals and to an output pin.

Refer to Figure 19-1 for a simplified diagram showing signal flow through the CLCx.

Possible configurations include:

- Combinatorial Logic
 - AND
 - NAND
 - AND-OR
 - AND-OR-INVERT
 - OR-XOR
 - OR-XNOR
- Latches
 - S-R
 - Clocked D with Set and Reset
 - Transparent D with Set and Reset
 - Clocked J-K with Reset

FIGURE 19-1: CLCx SIMPLIFIED BLOCK DIAGRAM

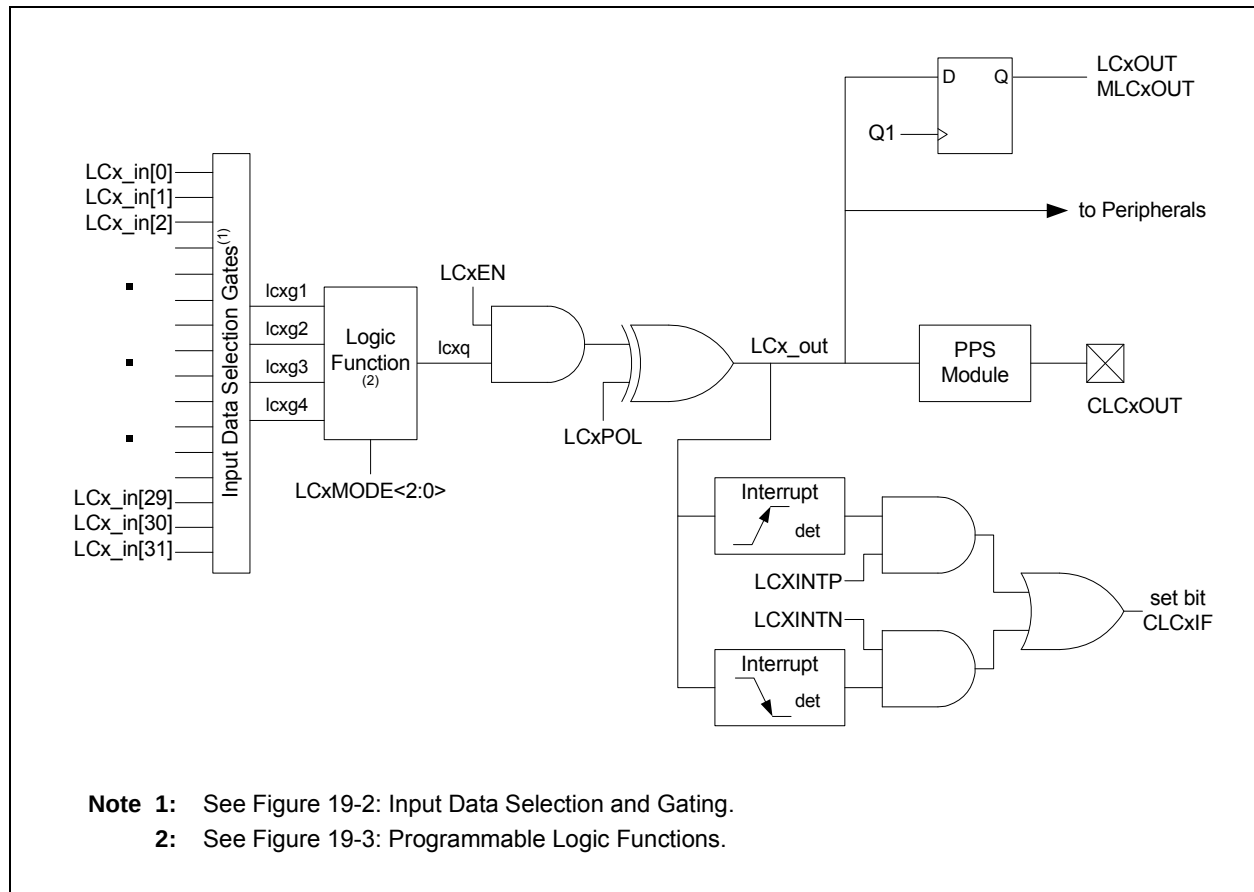


FIGURE 19-2: INPUT DATA SELECTION AND GATING

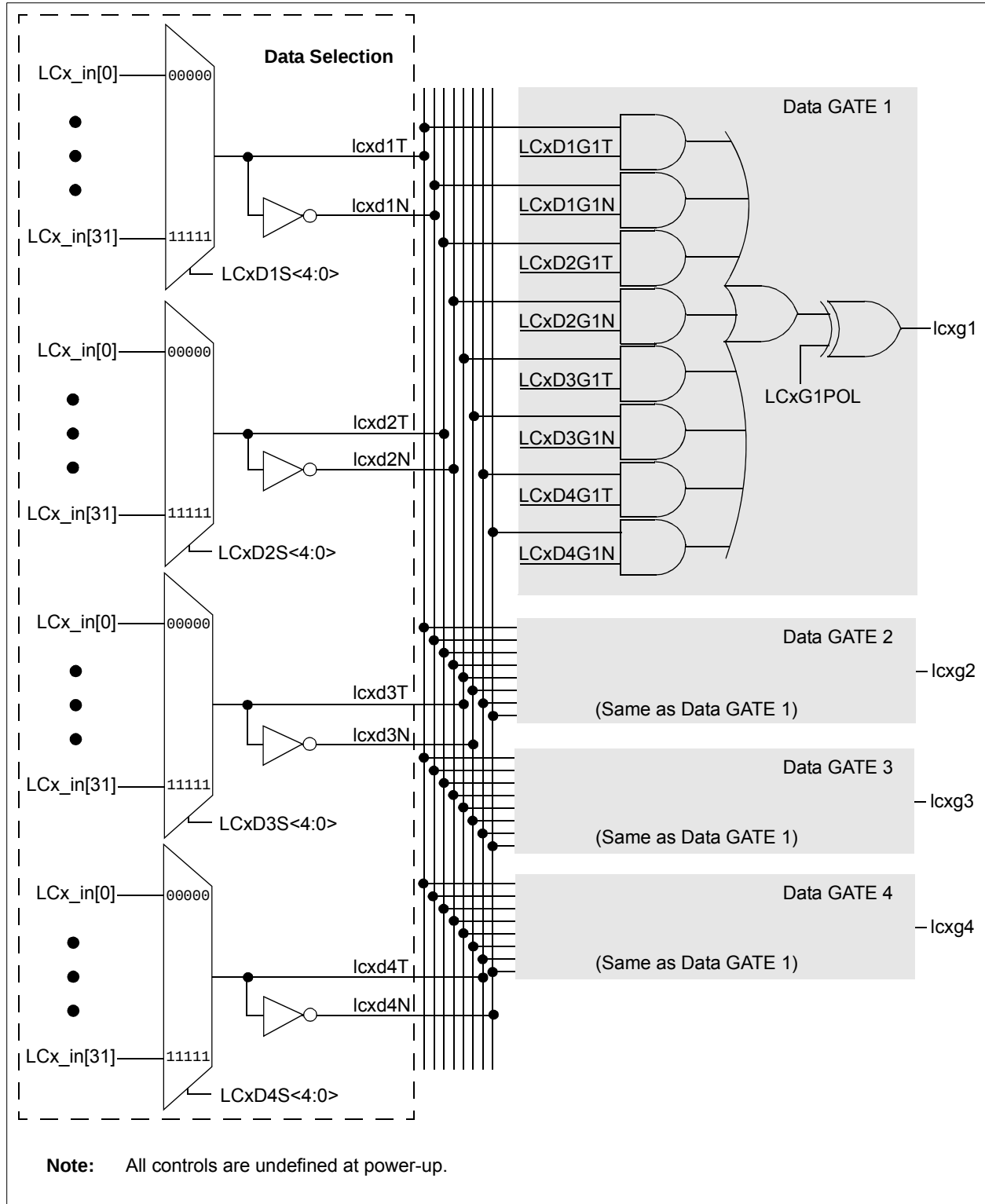
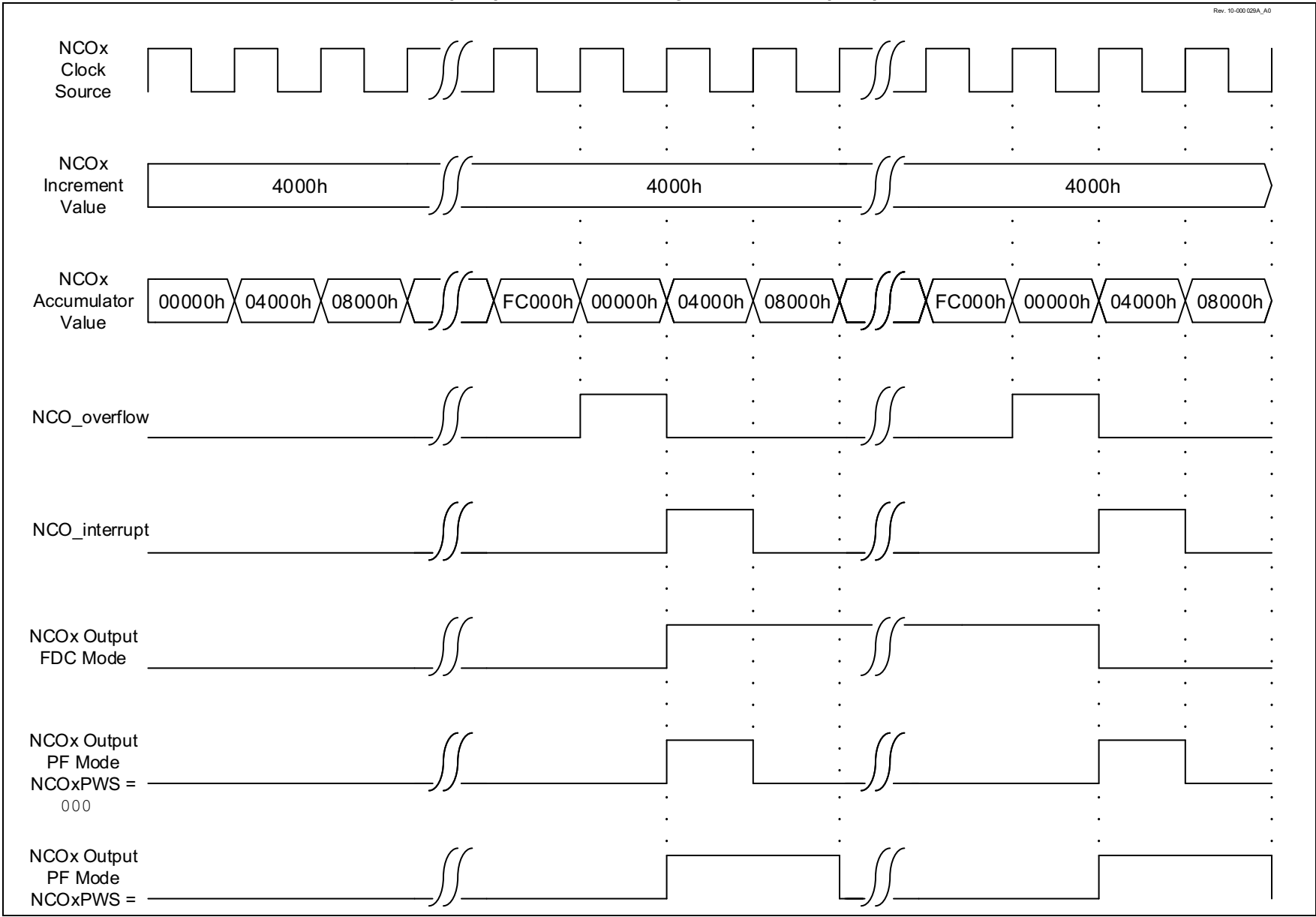


FIGURE 20-2: NCO – FIXED DUTY CYCLE (FDC) AND PULSE FREQUENCY MODE (PFM) OUTPUT OPERATION DIAGRAM



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NOTES:

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The CCPRxH register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

The 8-bit timer TMR2 register is concatenated with either the 2-bit internal system clock (Fosc), or two bits of the prescaler, to create the 10-bit time base. The system clock is used if the Timer2 prescaler is set to 1:1.

When the 10-bit time base matches the CCPRxH and 2-bit latch, then the CCPx pin is cleared (see Figure 29-4).

29.3.6 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is 10 bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 29-4.

EQUATION 29-4: PWM RESOLUTION

$$Resolution = \frac{\log[4(PR2 + 1)]}{\log(2)} \text{ bits}$$

If the pulse width value is greater than the period the assigned PWM pin(s) will remain unchanged.

TABLE 29-1: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (Fosc = 20 MHz)

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

TABLE 29-2: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (Fosc = 8 MHz)

PWM Frequency	1.22 kHz	4.90 kHz	19.61 kHz	76.92 kHz	153.85 kHz	200.0 kHz
Timer Prescale	16	4	1	1	1	1
PR2 Value	0x65	0x65	0x65	0x19	0x0C	0x09
Maximum Resolution (bits)	8	8	8	6	5	5

29.3.7 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the CCPx pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

29.3.8 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency. Any changes in the system clock frequency will result in changes to the PWM frequency. See **Section 6.0 “Oscillator Module (with Fail-Safe Clock Monitor)”** for additional details.

29.3.9 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the CCP registers to their Reset states.

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30.4.5 START CONDITION

The I²C specification defines a Start condition as a transition of SDA from a high to a low state while SCL line is high. A Start condition is always generated by the master and signifies the transition of the bus from an Idle to an Active state. Figure 30-12 shows wave forms for Start and Stop conditions.

A bus collision can occur on a Start condition if the module samples the SDA line low before asserting it low. This does not conform to the I²C Specification that states no bus collision can occur on a Start.

30.4.6 STOP CONDITION

A Stop condition is a transition of the SDA line from low-to-high state while the SCL line is high.

Note: At least one SCL low time must appear before a Stop is valid, therefore, if the SDA line goes low then high again while the SCL line stays high, only the Start condition is detected.

30.4.7 RESTART CONDITION

A Restart is valid any time that a Stop would be valid. A master can issue a Restart if it wishes to hold the bus after terminating the current transfer. A Restart has the same effect on the slave that a Start would, resetting all slave logic and preparing it to clock in an address. The master may want to address the same or another slave. Figure 30-13 shows the wave form for a Restart condition.

In 10-bit Addressing Slave mode a Restart is required for the master to clock data out of the addressed slave. Once a slave has been fully addressed, matching both high and low address bytes, the master can issue a Restart and the high address byte with the R/W bit set. The slave logic will then hold the clock and prepare to clock out data.

After a full match with R/W clear in 10-bit mode, a prior match flag is set and maintained until a Stop condition, a high address with R/W clear, or high address match fails.

30.4.8 START/STOP CONDITION INTERRUPT MASKING

The SCIE and PCIE bits of the SSPCON3 register can enable the generation of an interrupt in Slave modes that do not typically support this function. Slave modes where interrupt on Start and Stop detect are already enabled, these bits will have no effect.

FIGURE 30-12: I²C START AND STOP CONDITIONS

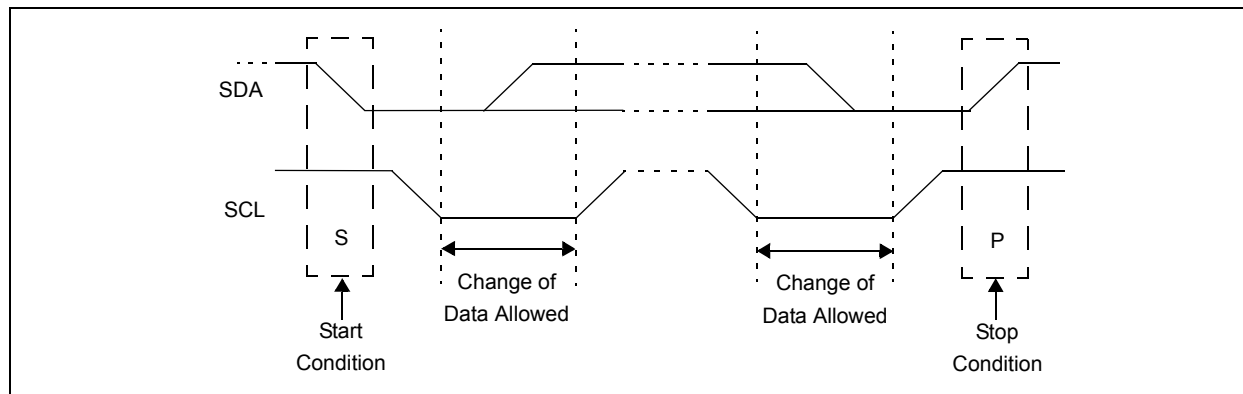
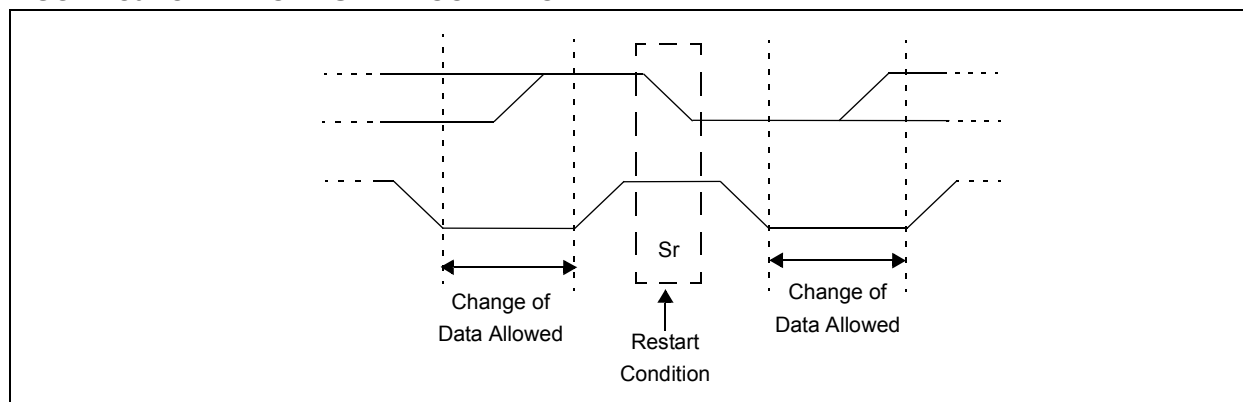


FIGURE 30-13: I²C RESTART CONDITION



30.5.2.1 7-bit Addressing Reception

This section describes a standard sequence of events for the MSSP module configured as an I²C slave in 7-bit Addressing mode. Figure 30-14 and Figure 30-15 is used as a visual reference for this description.

This is a step by step process of what typically must be done to accomplish I²C communication.

1. Start bit detected.
2. S bit of SSPSTAT is set; SSPIF is set if interrupt on Start detect is enabled.
3. Matching address with R/W bit clear is received.
4. The slave pulls SDA low sending an $\overline{\text{ACK}}$ to the master, and sets SSPIF bit.
5. Software clears the SSPIF bit.
6. Software reads received address from SSPBUF clearing the BF flag.
7. If SEN = 1; Slave software sets CKP bit to release the SCL line.
8. The master clocks out a data byte.
9. Slave drives SDA low sending an $\overline{\text{ACK}}$ to the master, and sets SSPIF bit.
10. Software clears SSPIF.
11. Software reads the received byte from SSPBUF clearing BF.
12. Steps 8-12 are repeated for all received bytes from the master.
13. Master sends Stop condition, setting P bit of SSPSTAT, and the bus goes idle.

30.5.2.2 7-bit Reception with AHEN and DHEN

Slave device reception with AHEN and DHEN set operate the same as without these options with extra interrupts and clock stretching added after the eighth falling edge of SCL. These additional interrupts allow the slave software to decide whether it wants to $\overline{\text{ACK}}$ the receive address or data byte, rather than the hardware. This functionality adds support for PMBus™ that was not present on previous versions of this module.

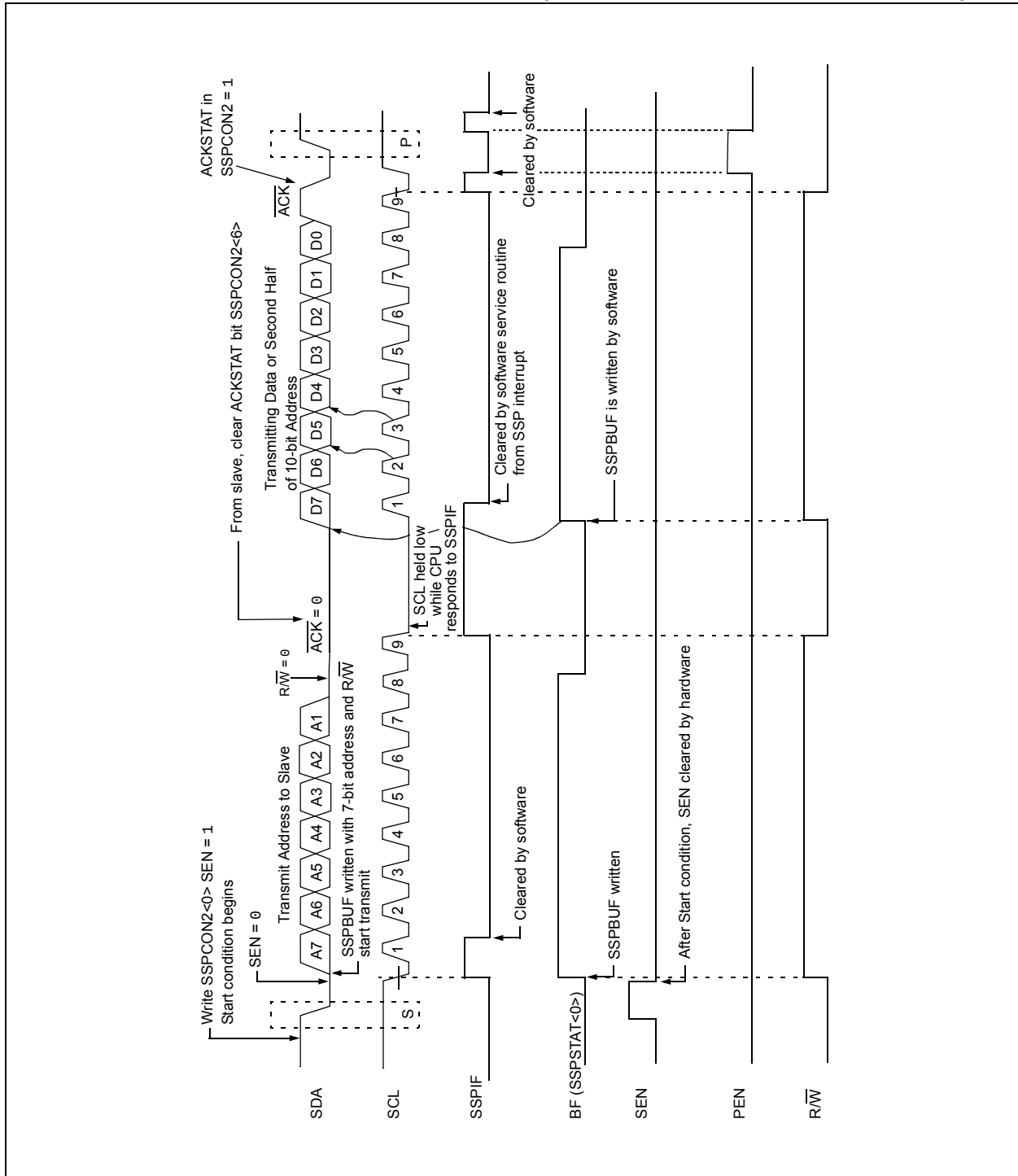
This list describes the steps that need to be taken by slave software to use these options for I²C communication. Figure 30-16 displays a module using both address and data holding. Figure 30-17 includes the operation with the SEN bit of the SSPCON2 register set.

1. S bit of SSPSTAT is set; SSPIF is set if interrupt on Start detect is enabled.
2. Matching address with R/W bit clear is clocked in. SSPIF is set and CKP cleared after the eighth falling edge of SCL.
3. Slave clears the SSPIF.
4. Slave can look at the ACKTIM bit of the SSPCON3 register to determine if the SSPIF was after or before the $\overline{\text{ACK}}$.
5. Slave reads the address value from SSPBUF, clearing the BF flag.
6. Slave sets $\overline{\text{ACK}}$ value clocked out to the master by setting ACKDT.
7. Slave releases the clock by setting CKP.
8. SSPIF is set after an $\overline{\text{ACK}}$, not after a NACK.
9. If SEN = 1 the slave hardware will stretch the clock after the $\overline{\text{ACK}}$.
10. Slave clears SSPIF.

Note: SSPIF is still set after the 9th falling edge of SCL even if there is no clock stretching and BF has been cleared. Only if NACK is sent to master is SSPIF not set

11. SSPIF set and CKP cleared after eighth falling edge of SCL for a received data byte.
12. Slave looks at ACKTIM bit of SSPCON3 to determine the source of the interrupt.
13. Slave reads the received data from SSPBUF clearing BF.
14. Steps 7-14 are the same for each received data byte.
15. Communication is ended by either the slave sending an $\overline{\text{ACK}} = 1$, or the master sending a Stop condition. If a Stop is sent and Interrupt on Stop Detect is disabled, the slave will only know by polling the P bit of the SSTSTAT register.

FIGURE 30-28: I²C MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESS)



31.1.2.8 Asynchronous Reception Setup:

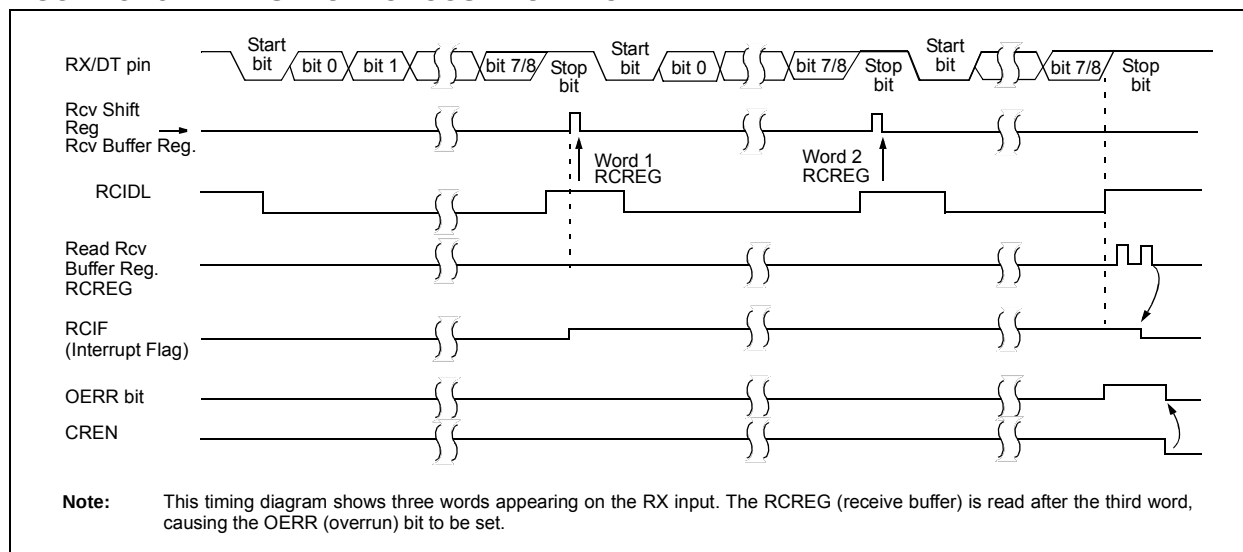
1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 31.4 “EUSART Baud Rate Generator (BRG)”**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set the RX9 bit.
6. Enable reception by setting the CREN bit.
7. The RCIF interrupt flag bit will be set when a character is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
8. Read the RCSTA register to get the error flags and, if 9-bit data reception is enabled, the ninth data bit.
9. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register.
10. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.

31.1.2.9 9-bit Address Detection Mode Setup

This mode would typically be used in RS-485 systems. To set up an Asynchronous Reception with Address Detect Enable:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 31.4 “EUSART Baud Rate Generator (BRG)”**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. Enable 9-bit reception by setting the RX9 bit.
6. Enable address detection by setting the ADDEN bit.
7. Enable reception by setting the CREN bit.
8. The RCIF interrupt flag bit will be set when a character with the ninth bit set is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
9. Read the RCSTA register to get the error flags. The ninth data bit will always be set.
10. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register. Software determines if this is the device's address.
11. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.
12. If the device has been addressed, clear the ADDEN bit to allow all received data into the receive buffer and generate interrupts.

FIGURE 31-5: ASYNCHRONOUS RECEPTION



31.4.2 AUTO-BAUD OVERFLOW

During the course of automatic baud detection, the ABDOVF bit of the BAUDxCON register will be set if the baud rate counter overflows before the fifth rising edge is detected on the RX pin. The ABDOVF bit indicates that the counter has exceeded the maximum count that can fit in the 16 bits of the SPxBRGH:SPxBRGL register pair. The overflow condition will set the RCIF flag. The counter continues to count until the fifth rising edge is detected on the RX pin. The RCIDL bit will remain false ('0') until the fifth rising edge, at which time, the RCIDL bit will be set. If the RCREG is read after the overflow occurs but, before the fifth rising edge, the fifth rising edge will set the RCIF again.

Terminating the auto-baud process early to clear an overflow condition will prevent proper detection of the sync character's fifth rising edge. If any falling edges of the sync character have not yet occurred when the ABDEN bit is cleared, then those will be falsely detected as Start bits. The following steps are recommended to clear the overflow condition:

1. Read RCREG to clear RCIF.
2. If RCIDL is zero then wait for RCIF and repeat step 1.
3. Clear the ABDOVF bit.

31.4.3 AUTO-WAKE-UP ON BREAK

During Sleep mode, all clocks to the EUSART are suspended. Because of this, the Baud Rate Generator is inactive and a proper character reception cannot be performed. The Auto-Wake-up feature allows the controller to wake-up due to activity on the RX/DT line. This feature is available only in Asynchronous mode.

The Auto-Wake-up feature is enabled by setting the WUE bit of the BAUDCON register. Once set, the normal receive sequence on RX/DT is disabled, and the EUSART remains in an Idle state, monitoring for a wake-up event independent of the CPU mode. A wake-up event consists of a high-to-low transition on the RX/DT line. (This coincides with the start of a Sync Break or a wake-up signal character for the LIN protocol.)

The EUSART module generates an RCIF interrupt coincident with the wake-up event. The interrupt is generated synchronously to the Q clocks in normal CPU operating modes (Figure 31-7), and asynchronously if the device is in Sleep mode (Figure 31-8). The interrupt condition is cleared by reading the RCREG register.

The WUE bit is automatically cleared by the low-to-high transition on the RX line at the end of the Break. This signals to the user that the Break event is over. At this point, the EUSART module is in Idle mode waiting to receive the next character.

31.4.3.1 Special Considerations

Break Character

To avoid character errors or character fragments during a wake-up event, the wake-up character must be all zeros.

When the wake-up is enabled the function works independent of the low time on the data stream. If the WUE bit is set and a valid non-zero character is received, the low time from the Start bit to the first rising edge will be interpreted as the wake-up event. The remaining bits in the character will be received as a fragmented character and subsequent characters can result in framing or overrun errors.

Therefore, the initial character in the transmission must be all '0's. This must be ten or more bit times, 13-bit times recommended for LIN bus, or any number of bit times for standard RS-232 devices.

Oscillator Start-up Time

Oscillator start-up time must be considered, especially in applications using oscillators with longer start-up intervals (i.e., LP, XT or HS/PLL mode). The Sync Break (or wake-up signal) character must be of sufficient length, and be followed by a sufficient interval, to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART.

WUE Bit

The wake-up event causes a receive interrupt by setting the RCIF bit. The WUE bit is cleared in hardware by a rising edge on RX/DT. The interrupt condition is then cleared in software by reading the RCREG register and discarding its contents.

To ensure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process before setting the WUE bit. If a receive operation is not occurring, the WUE bit may then be set just prior to entering the Sleep mode.

PIC16(L)F1713/6

TABLE 34-3: POWER-DOWN CURRENTS (I_{PD})^(1,2) (CONTINUED)

PIC16LF1713/6			Operating Conditions: (unless otherwise stated) Low-Power Sleep Mode					
PIC16F1713/6			Low-Power Sleep Mode, VREGPM = 1					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V _{DD}	Note
D030		—	250	—	—	μA	1.8	ADC Current (Note 3), conversion in progress
		—	250	—	—	μA	3.0	
D030		—	280	—	—	μA	2.3	ADC Current (Note 3), conversion in progress
		—	280	—	—	μA	3.0	
		—	280	—	—	μA	5.0	
D031		—	250	650	—	μA	3.0	Op Amp (High-power)
D031		—	250	650	—	μA	3.0	Op Amp (High-power)
		—	350	850	—	μA	5.0	
D032		—	250	600	—	μA	1.8	Comparator, CxSP = 0
		—	300	650	—	μA	3.0	
D032		—	280	600	—	μA	2.3	Comparator, CxSP = 0 VREGPM = 0
		—	300	650	—	μA	3.0	
		—	310	650	—	μA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** The peripheral current is the sum of the base I_{PD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max values should be used when calculating total current consumption.
- Note 2:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.
- Note 3:** ADC clock source is FRC.

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TABLE 34-26: I²C BUS DATA REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	Symbol	Characteristic		Min.	Max.	Units	Conditions
SP100*	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5T _{CY}	—		
SP101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5T _{CY}	—		
SP102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1C _B	300	ns	C _B is specified to be from 10-400 pF
SP103*	TF	SDA and SCL fall time	100 kHz mode	—	250	ns	
			400 kHz mode	20 + 0.1C _B	250	ns	C _B is specified to be from 10-400 pF
SP106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
SP107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	(Note 2)
			400 kHz mode	100	—	ns	
SP109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	(Note 1)
			400 kHz mode	—	—	ns	
SP110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
SP111	C _B	Bus capacitive loading		—	400	pF	

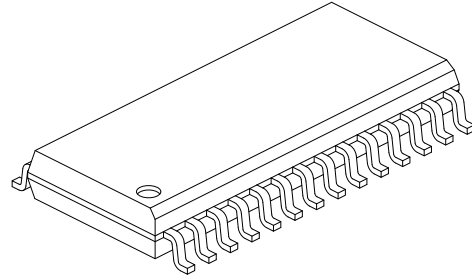
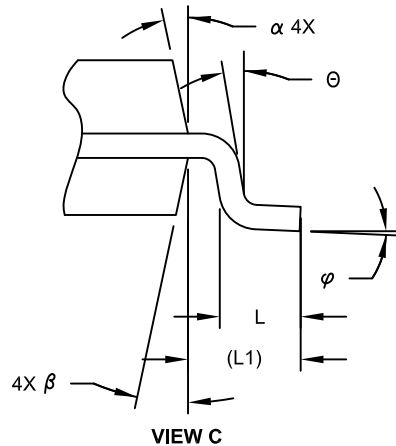
* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A Fast mode (400 kHz) I²C bus device can be used in a Standard mode (100 kHz) I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the low period of the SCL signal. If such a device does stretch the low period of the SCL signal, it must output the next data bit to the SDA line TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2